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## Fan Controller and Remote Temperature Sensor with SMBus Serial Interface

#### **General Description**

The MAX1669 fan controller includes a precise digital thermometer that reports the temperature of a remote sensor. The remote sensor is a diode-connected transistor—typically a low-cost, easily mounted 2N3906 PNP type—replacing conventional thermistors or thermocouples. Remote accuracy is  $\pm 3^{\circ}$ C for transistors from multiple manufacturers, with no calibration needed. The MAX1669 has an independent fan controller with a low-current logic output requiring external power components to interface to a DC brushless fan. The fan controller has two modes of operation: a low-frequency (20Hz to 160Hz) PWM mode intended for driving the fan motor, or a high-impedance DAC output that generates a variable DC control voltage. In PWM mode, the FAN frequency can be synchronized to an external clock.

Other key features include general-purpose inputs/outputs (GPIOs) for fan presence detection and a thermostat output intended as a fan override signal in case the host system loses the ability to communicate. The internal ADC has a wide input voltage range and gives overrange readings when too large an input voltage is applied. Other error-checking includes temperature out-of-range indication and diode open/short faults.

The MAX1669 is available in a space-saving 16-pin QSOP package that allows it to fit adjacent to the SLOT1 connector.

#### **Applications**

Pentium<sup>®</sup> CPU Cooling Desktop Computers Notebook Computers Servers Workstations

Typical Operating Circuit appears at end of data sheet.



- Measures Remote CPU Temperature
- No Calibration Required
- ♦ 20Hz to 160Hz PWM Output for Fan
- PWM Frequency Sync Input (260kHz)
- ♦ Flexible Fan Interface: Linear or PWM
- SMBus 2-Wire Serial Interface
- Programmable Under/Overtemperature Alarms
- ♦ ALERT Latched Interrupt Output
- ♦ OVERT Thermostat Output
- Two GPIO Pins
- Write-Once Configuration Protection
- Supports SMBus Alert Response
- ♦ ±3°C Temperature Accuracy (-40°C to +125°C, remote)
- ♦ 3µA Standby Supply Current
- ♦ +3V to +5.5V Supply Range
- Small 16-Pin QSOP Package

#### **Ordering Information**

# PARTTEMP. RANGEPIN-PACKAGEMAX1669EEE-40°C to +85°C16 QSOP

#### Pin Configuration



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#### **ABSOLUTE MAXIMUM RATINGS**

V <sub>CC</sub> to AGND DXP, ADD_ to AGND DXN to AGND.	0.3V to (V <sub>CC</sub> + 0.3V)
SMBCLK, SMBDATA, ALERT, SYNC,	
I/O1, I/O2, OVERT, FAN to AGND	0.3V to +6V
FAN to PGND	0.3V to (V <sub>CC</sub> + 0.3V)
PGND to AGND	0.3V to +0.3V
PWM Current	50mA to +50mA
SMBDATA Current	1mA to +50mA
I/O1, I/O2 Current	1mA to +25mA

DXN Current	±1mA
ESD Protection (all pins, Human Body Model)	2000V
Continuous Power Dissipation ( $T_A = +70^{\circ}C$ )	
16-Pin QSOP (derate 8.30mW/°C above +70°C)	.667mW
Operating Temperature Range (extended)55°C to	+125°C
Junction Temperature	+150°C
Storage Temperature Range65°C to	
Lead Temperature (soldering, 10s)	+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### **ELECTRICAL CHARACTERISTICS**

(V<sub>CC</sub> = +3.3V,  $T_A = 0^{\circ}C$  to +85°C, unless otherwise noted. Typical values are at  $T_A = +25^{\circ}C$ .)

PARAMETER	CONDITIONS			MIN	ТҮР	MAX	UNITS
ADC AND POWER SUPPLY			L. C.				
Resolution (Note 1)	Monotonicity guarantee	ed		8			Bits
Temperature Error, Remote Diode (Note 2)	$T_R = 0^{\circ}C$ to +100°C, diode ideality factor = 1.013			-3		3	°C
Supply Voltage Range			3		5.5	V	
Undervoltage Lockout Threshold	V <sub>CC</sub> input, disables A/D conversion, rising edge			2.6	2.8	2.95	V
Undervoltage Lockout Hysteresis					50		mV
Power-On Reset Threshold	V <sub>CC</sub> , falling edge			1	1.9	2.5	V
POR Threshold Hysteresis					50		mV
Standby Supply Current	SMBus static				3	10	
Standby Supply Current	SMBCLK at 10kHz				3		μA
Average Operation Supply Current	Autoconvert mode, average measured over 1s		FAN output set to 150Hz mode		75	150	μA
Average Operating Supply Current			FAN output set to DAC mode		360		μA
Conversion Time	From stop bit to conve	rsion	complete	47	62	78	ms
Conversion Rate	Autoconvert mode			1.6	2	2.4	Hz
Demote Diada Courses Current	V <sub>DXP</sub> forced to V <sub>DXN</sub>	Hig	jh level	80	100	120	
Remote-Diode Source Current	+ 0.65V	Lov	w level	8	10	12	μA
DXN Source Voltage					0.7		V
FAN OUTPUT			I				
FAN Output Source Current	PWM mode, VFAN force	ed to	2.9V	10			mA
FAN Output Sink Current	PWM mode, V <sub>FAN</sub> force	ed to	0.4V			-10	mA

#### **ELECTRICAL CHARACTERISTICS (continued)**

(V<sub>CC</sub> = +3.3V,  $T_A = 0^{\circ}C$  to +85°C, unless otherwise noted. Typical values are at  $T_A = +25^{\circ}C$ .)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
FAN PWM Frequency Error	PWM mode, any setting	-20		+20	%
FAN Total Unadjusted Error	DAC mode, any setting, $R_L = 10k\Omega$ to GND	-4		4	%FS
FAN Output Voltage High	DAC mode, FAN duty factor = 1111b, I <sub>OUT</sub> = 5mA	2.96	3.06		V
FAN Output Voltage Low	DAC mode, FAN duty factor = 0000b, I <sub>OUT</sub> = -5mA		0.05	0.2	V
SYNC Capture Range		140	260	400	kHz
SYNC Input High Period		500			ns
SYNC Input Low Period		500			ns
SMBus INTERFACE (Figures 7, 8)					
Logic Input High Voltage	ADD_, I/O1, I/O2, SYNC, SMBCLK, SMBDATA; V <sub>CC</sub> = 3V to 5.5V	2.1			V
Logic Input Low Voltage	ADD_, I/O1, I/O2, SYNC, SMBCLK, SMBDATA; V <sub>CC</sub> = 3V to 5.5V			0.8	V
SMBDATA, ALERT, OVERT, I/O1, I/O2 Output Low Sink Current	Pin forced to 0.4V	6			mA
ALERT, OVERT, I/O1, I/O2 Output High Leakage Current	Pin forced to 5.5V			1	μA
Logic Input Current	Logic inputs forced to V <sub>CC</sub> or GND	-1		1	μA
SMBus Input Capacitance	SMBCLK, SMBDATA		5		pF
SMBus Clock Frequency	(Note 3)	DC		100	kHz
SMBCLK Clock Low Time (t <sub>LOW</sub> )	10% to 10% points	4.7			μs
SMBCLK Clock High Time (t <sub>HIGH</sub> )	90% to 90% points	4			μs
SMBus Rise Time	SMBCLK, SMBDATA, 10% to 90% points			1	μs
SMBus Fall Time	SMBCLK, SMBDATA, 90% to 10% points			300	ns
SMBus Start Condition Setup Time		4.7			μs
SMBus Repeated Start Condition Setup Time (tsu:sta)	90% to 90% points	500			ns
SMBus Start Condition Hold Time (tHD:STA)	10% of SMBDATA to 90% of SMBCLK	4			μs
SMBus Stop Condition Setup Time (t <sub>SU:STO</sub> )	90% of SMBCLK to 10% of SMBDATA	4			μs
SMBus Data Valid to SMBCLK Rising-Edge Time (t <sub>SU:DAT</sub> )	10% or 90% of SMBDATA to 10% of SMBCLK	250			ns
SMBus Data-Hold Time (t <sub>HD:DAT</sub> )	(Note 4)	0			μs
SMBus Bus-Free Time (t <sub>BUF</sub> )	Between start/stop conditions	4.7			μs
SMBCLK Falling Edge to SMBus Data-Valid Time	Master clocking-in data			1	μs

**ELECTRICAL CHARACTERISTICS** 

(V<sub>CC</sub> = +3.3V,  $T_A = -40^{\circ}C$  to +85°C, unless otherwise noted.) (Note 5)

PARAMETER	CONDITIONS	MIN	MAX	UNITS
ADC AND POWER SUPPLY	1			
Temperature Resolution (Note 1)	Monotonicity guaranteed	8		Bits
Temperature Error, Remote Diode (Note 2)	$T_R = -55^{\circ}C$ to $+125^{\circ}C$ , diode ideality factor = 1.013	-5	5	°C
Supply Voltage Range		3	5.5	V
Average Operating Supply Current	Autoconvert mode, average measured over 1sec, FAN output set to 150Hz mode		100	μA
Conversion Time	From stop bit to conversion complete	47		ms
Conversion Rate	Autoconvert mode	1.6	2.4	Hz
FAN OUTPUT	· · · · · ·			1
FAN Output Source Current	PWM mode, V <sub>FAN</sub> forced to 2.9V	10		mA
FAN Output Sink Current	PWM mode, V <sub>FAN</sub> forced to 0.4V		-10	mA
FAN PWM Frequency Error	PWM mode, any setting	-25	+25	%
FAN Total Unadjusted Error	DAC mode, any setting, $R_L = 10k\Omega$ to GND	-5	5	%FS
FAN Output Voltage High	DAC mode, FAN duty factor = 1111b, I <sub>OUT</sub> = 5mA	2.94		V
FAN Output Voltage Low	DAC mode, FAN duty factor = 0000b, I <sub>OUT</sub> = -5mA		0.2	V
SMBus INTERFACE				
Logic Input High Voltage	ADD_, I/O1, I/O2, SYNC, SMBCLK, SMBDATA; $V_{CC} = 3V$ to 5.5V	2.1		V
Logic Input Low Voltage	ADD_, I/O1, I/O2, SYNC, SMBCLK, SMBDATA; $V_{CC} = 3V$ to 5.5V		0.8	V
SMBDATA, ALERT, OVERT, I/O1, I/O2 Output Low Sink Current	Pin forced to 0.4V	6		mA
ALERT, OVERT, I/O1, I/O2 Output High Leakage Current	Pin forced to 5.5V		1	μA
Logic Input Current	Logic inputs forced to V <sub>CC</sub> or GND	-1	1	μA

Note 1: Guaranteed but not 100% tested.

Note 2: T<sub>R</sub> is the junction temperature of the remote diode. The temperature error specification is optimized to and guaranteed for a diode-connected 2N3906 transistor with ideality factor = 1.013. Variations in the ideality factor "m" of the actual transistor used will increase the temperature error by \*. See the Temperature Error vs. Remote Diode Temperature graph in the *Typical Operating Characteristics* for typical temperature errors using several random 2N3906s. See *Remote Diode Selection* for remote diode forward-voltage requirements.

Note 3: The SMBus logic block is a static design that works with clock frequencies down to DC. While slow operation is possible, it violates the 10kHz minimum clock frequency and SMBus specifications, and may monopolize the bus.

Note 4: Note that a transition must internally provide at least a hold time in order to bridge the undefined region (300ns max) of SMBCLK's falling edge.

Note 5: Specifications to -40°C are guaranteed by design and not production tested.

$$^{*}\Delta T = \left(\frac{1.013}{m} - 1\right) \left(273.15k + T_{R}\right) (^{\circ}C)$$



(Temperature error = measured - actual,  $T_A = +25^{\circ}C$ , unless otherwise noted.)



#### **Typical Operating Characteristics (continued)**

(Temperature error = measured - actual,  $T_A = +25^{\circ}C$ , unless otherwise noted.)





#### **Pin Description**

PIN	NAME	FUNCTION
1	I/O1	General-Purpose Open-Drain Logic Input/Output 1. I/O1 is intended for driving LEDs, driving power-plane switching MOSFETs, or detecting fan presence or chassis intrusion.
2	I/O2	General-Purpose Open-Drain Logic Input/Output 2. I/O2 is intended for driving LEDs, driving power-plane switching MOSFETs, or detecting fan presence or chassis intrusion.
3	ADD0	SMBus Address Select Pin 0. See Table 11.
4	ADD1	SMBus Address Select Pin 1. See Table 11.
5	ADD2	SMBus Address Select Pin 2. See Table 11.
6	AGND	Analog Ground
7	DXN	Combined Current Sink and ADC Negative Input from Remote Diode. DXN is normally biased to a diode voltage above ground.
8	DXP	Combined Current Source and ADC Positive Input from Remote Diode. Place a 2200pF capacitor between DXP and DXN for noise filtering.
9	Vcc	Supply Voltage Input, +3V to +5.5V. Bypass to AGND with a $0.1\mu$ F capacitor.
10	SYNC	Oscillator Synchronization Input. Connect to AGND to use internal clock. Capture range is 140kHz to 400kHz. The synchronization signal is internally applied to the FAN PWM clock. See Table 5 for synchronized frequencies.
11	FAN	Fan-Control Logic Output. Swings from PGND to V_{CC} in PWM mode, or PGND to 0.94 $\cdot$ V_{CC} in DAC mode.
12	PGND	Power Ground
13	SMBCLK	SMBus Serial-Clock Input
14	SMBDATA	Open-Drain SMBus Serial-Data Input/Output
15	ALERT	Active-Low, Open-Drain SMBus Alert (interrupt) Output
16	OVERT	Active-Low, Open-Drain Thermostat Output. Activated by TCRIT threshold

M /X /M



Figure 1. MAX1669 Temperature Sensor Functional Diagram

#### \_Detailed Description

The MAX1669 temperature sensor is designed to work with an external microcontroller ( $\mu$ C) or other intelligent devices in computer fan-control applications. The  $\mu$ C is typically a power-management or keyboard controller, generating SMBus serial commands by "bit-banging" general-purpose input/output (GPIO) pins or through a dedicated SMBus interface block.

Essentially an 8-bit serial analog-to-digital converter (ADC) with a sophisticated front end, the temperature measurement channel contains a switched-current source, a multiplexer, and an integrating ADC. Temperature data from the ADC is loaded into a data register, where it is automatically compared with data previously stored in over/undertemperature alarm registers and the critical register (Figure 1).



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The PWM or DAC fan control circuitry is completely independent from the temperature measurement, and software closes the temperature-control feedback loop (Figure 2).

#### **ADC and Multiplexer**

The ADC is an averaging type that integrates over a 62ms period (typ), with excellent noise rejection. The multiplexer automatically steers bias currents through the remote diode, measures the forward voltage, and calculates the temperature.



Figure 2. MAX1669 Fan-Control Functional Diagram

The DXN input is biased at 0.7V above ground by an internal diode to set up the analog-to-digital (A/D) inputs for a differential measurement. The worst-case DXP-DXN differential input voltage range is 0.21V to 0.95V. Diode voltages that are outside the ADC input range cause overrange indications rather than non-monotonic readings. Overrange readings will return +127°C. Excess resistance in series with the remote diode causes approximately +1/2°C error/ $\Omega$ . Likewise, 200µV of offset voltage forced on DXP-DXN causes approximately +1°C error.

#### **A/D Conversion Sequence**

When the device is taken out of standby mode, the result of the measurement is available one conversion time later (78ms max). If the ADC is busy, the results of the previous conversion are always available. Toggling the standby mode on and off is a good way to initiate a new conversion since this action resets the rate timer.

#### Low-Power Standby Mode

Supply-current drain during the 62ms conversion period is 500µA. Between conversions, the instantaneous supply current is 18 $\mu$ A. In standby mode, supply current drops to 3 $\mu$ A and the fan output is disabled.

#### **SMBus Digital Interface**

From a software perspective, the MAX1669 appears as a set of byte-wide registers that contain temperature data, alarm threshold values, or control bits. A standard SMBus 2-wire serial interface is used to read temperature data and write control bits and alarm threshold data.

The MAX1669 employs four standard SMBus protocols: write byte, read byte, send byte, and receive byte (Figure 3). The two shorter protocols (receive and send) allow quicker transfers, provided that the correct data register was previously selected by a write or read byte instruction. Use caution with the shorter protocols in multimaster systems since a second master could overwrite the command byte without informing the first master.

The temperature data format is 7 bits plus sign in two's complement form for each channel, with the LSB representing  $+1^{\circ}$ C (Table 1), MSB transmitted first. Measurements are offset by  $+1/2^{\circ}$ C to minimize internal rounding errors; for example,  $+99.5^{\circ}$ C to  $+100.4^{\circ}$ C is reported as  $+100^{\circ}$ C.

#### **Alarm Threshold Registers**

Three registers store alarm threshold data, with hightemperature (T<sub>HIGH</sub>) and low-temperature (T<sub>LOW</sub>) registers that activate the ALERT output, and a critical overtemperature register (T<sub>CRIT</sub>) that activates the OVERT output. If a measured temperature equals or exceeds the T<sub>HIGH</sub> or T<sub>LOW</sub> threshold value, an ALERT interrupt is asserted. Do not set the T<sub>CRIT</sub> register to values outside of the temperatures in Table 1.

The power-on-reset (POR) state of the T<sub>HIGH</sub> register is full scale (0111 1111b or +127°C). The POR state of the T<sub>LOW</sub> register is 1100 1001b or -55°C. The POR state of the T<sub>CRIT</sub> register is 0110 0100b or +100°C.

#### **OVERT** Thermostat Output

The OVERT output is a self-clearing interrupt output that is activated when the temperature equals or exceeds  $T_{CRIT}$ . OVERT normally goes low when active, but this polarity can be changed through the configuration register. The latch is cleared when the temperature reading is equal to or less than  $T_{CRIT}$  minus 5°C, which provides for 5°C of hysteresis.

The ALERT and OVERT comparisons are made after each conversion, and at the end of a write command to their respective temperature limit registers. For example, if the limit is changed while the device is in standby

S	ADDRES	S	WR	ACK COMMA		AND	ACK	DAT	TA	ACK		Ρ
1	7 bits		1	1 8 bits 1			1	8 bits		1		1
lead l	7-bit slave a equivalent to Byte Format				ommand b gister you	-	cts which ng to	set by the	e comma ls, config	oes into the and byte (to juration mas	set	
	-	WR	АСК	COMMAND	ACK	S	ADDRESS	RD	ACK	DATA	Ā	P
S	ADDRESS	WR	AUN									
<b>S</b> 1	ADDRESS       7 bits	1	1	8 bits	1	1	7 bits	1	1	8 bits	1	1

Figure 3. SMBus Protocols

#### Table 1. Data Format (Two's Complement)

	1			1
TEMP (°C)	ROUNDED TEMP (°C)		AITAL OUT DATA BITS MSBs	
+130.00	+127	0	111	1111
+127.00	+127	0	111	1111
+126.50	+127	0	111	1111
+126.00	+126	0	111	1110
+25.25	+25	0	001	1001
+0.50	+1	0	000	0001
+0.25	+0	0	000	0000
+0.00	+0	0	000	0000
-0.25	+0	0	000	0000
-0.50	+0	0	000	0000
-0.75	-1	1	111	1111
-1.00	-1	1	111	1111
-25.00	-25	1	110	0111
-25.50	-26	1	110	0110
-54.75	-55	1	100	1001
-55.00	-55	1	100	1001
-65.00	-65	1	011	1111
-70.00	-65	1	011	1111

mode, the ALERT and OVERT outputs respond correctly according to the last valid A/D result.

Note that the  $\overline{\text{ALERT}}$  output does not respond to  $T_{\text{CRIT}}$  ( $\overline{\text{OVERT}}$ ) comparisons.

The OVERT latch can implement an override control to the FAN output, which forces the fan to V<sub>CC</sub> whenever the T<sub>CRIT</sub> threshold is crossed. This override switch is the backup fan control loop, and is enabled through the FAN ON bit in the configuration register (bit 2). Note that changing the duty to 100% in this way doesn't affect the contents of the DUTY register, and the FAN output reverts to the preprogrammed duty factor (or DAC voltage) when the OVERT latch is reset.

#### **Diode Fault Alarm**

A continuity fault detector at DXP detects whether the remote diode has an open-circuit condition, short-circuit to GND, or short-circuit DXP-to-DXN condition. At the beginning of each conversion, the diode fault is checked and the status byte updated. This fault detector is a simple voltage detector; DXP rising above V<sub>CC</sub> - 1V or falling below DXN + 40mV constitutes a fault condition. Also, if the ADC has an extremely low differential input voltage, the diode is assumed to be shorted and a fault occurs. Note that the diode fault isn't checked until a conversion is initiated, so immediately after power-on reset the status byte indicates no fault is present even if the diode path is broken. Any diode fault will return a +127°C fault reading and cause ALERT to go low.

#### **ALERT** Interrupts

The ALERT interrupt output signal is latched and can only be cleared by reading the Alert Response address. Interrupts are generated in response to  $T_{HIGH}$ and  $T_{LOW}$  comparisons, when there is a fault with the remote diode, or when a high-to-low or low-to-high transition at I/O1 or I/O2 is detected.

The interrupt does not halt automatic conversions; new temperature data continues to be available over the SMBus interface after ALERT is asserted. The interrupt output is open-drain so that devices can share a common interrupt line. The interface responds to the SMBus Alert Response address, an interrupt pointer return-address feature (see the *Alert Response Address* section).

The ALERT interrupt latch is set when the temperature exceeds an ALARM threshold. ALERT will not be set again until the threshold is reprogrammed. This prevents the ALERT latch from being set again during the interval between reading the Alert Response address and updating the offending alarm threshold. Note that this behavior is identical to the MAX1618 but is slightly different from the MAX1617, which continues to interrupt until the temperature no longer exceeds the alarm threshold. Note also that if some new alarm condition occurs, such as crossing the other alarm threshold or having a GPIO transition, a new interrupt is generated.

#### **ALERT Response Address**

The SMBus Alert Response interrupt pointer provides quick fault identification for simple slave devices that lack the complex, expensive logic needed to be a bus master. Upon receiving an ALERT interrupt signal, the host master can broadcast a receive byte transmission to the Alert Response slave address (0001100b). Then any slave device that generated an interrupt attempts to identify itself by putting its own address on the bus (Table 2).

The Alert Response can activate several different slave devices simultaneously, similar to the I<sup>2</sup>C General Call. If more than one slave attempts to respond, bus arbitration rules apply, and the device with the lower address code wins. The losing device does not generate an acknowledge and continues to hold the ALERT line low until serviced. Successful reading of the alert response address clears the interrupt latch.

#### **Command Byte Functions**

The 8-bit command byte register (Table 3) is the master index that points to the MAX1669's other registers. The register's POR state is 00000001b, so a receive byte transmission (a protocol that lacks the command byte)

# Table 2. Read Format for the AlertResponse Address (0001100b)

•	
NAME	FUNCTION
ADD7	
ADD6	
ADD5	
ADD4	Provide the MAX1669 slave address
ADD3	
ADD2	
ADD1	
1	Logic 1
	ADD7 ADD6 ADD5 ADD4 ADD3 ADD2

that occurs immediately after POR returns the current remote temperature data.

#### **One-Shot Conversion**

The one-shot command immediately forces a new conversion cycle to begin. In software standby mode (STBY bit = 1), a new conversion starts, after which the device returns to standby mode. If a conversion is in progress when a one-shot command is received, the command is ignored. If a one-shot command is received in autoconvert mode (STBY bit = 0) between conversions, a new conversion begins, the conversion rate timer is reset, and the next automatic conversion takes place after a full period.

#### **Configuration Byte Functions**

The configuration byte register (Table 4) is used to mask (disable) interrupts, set the OVERT output polarity, and put the device in software standby mode. Bit 1 of the configuration byte in Table 4 is for factory use only and must be set to 1 (value at POR). This register's contents can be read back over the serial interface.

#### FAN PWM Frequency and Duty Factor Control

The fan speed is controlled by the average voltage applied to the fan. The average voltage is equal to the product of the motor power-supply voltage and the duty factor. The duty factor is equal to zero upon startup and it is software controlled. The FAN output frequency is controlled by the PWM frequency register unless this register's code is set to 1111b (Table 5). A PWM frequency code of 1111b puts the FAN output in DAC mode. For all other codes, the FAN frequency is in the 20Hz to 160Hz range as shown in Table 5. For the possible synchronized frequencies, also see Table 5. The FAN output duty factor is controlled by the FAN duty factor register unless the PWM frequency code is



REGISTER	COMMAND	POR STATE	FUNCTION
	00h	N/A	Reserved for future use
RTEMP	01h	N/A	Read latest temperature
RSTAT	02h	N/A	Read status byte (temp flags, I/O_ states)
RCFG	03h	0000 0010b	Read configuration byte
	04h	N/A	Reserved for future use
	05h	N/A	Reserved for future use
	06h	N/A	Reserved for future use
RHI	07h	0111 1111b	Read T <sub>HIGH</sub> limit
RLOW	08h	1100 1001b	Read T <sub>LOW</sub> limit
WCFG	09h	N/A	Write configuration byte
	0Ah	N/A	Reserved for future use
	0Bh	N/A	Reserved for future use
	0Ch	N/A	Reserved for future use
WHI	0Dh	N/A	Write T <sub>HIGH</sub> limit
WLOW	0Eh	N/A	Write T <sub>LOW</sub> limit
OSHT	0Fh	N/A	One-shot command. Will execute a single conversion even if the device is in software standby.
RCRIT	10h	0110 0100b	Read T <sub>CRIT</sub> limit
RPROT	11h	d0000 0000b	Read write-once protection byte
RFREQ	12h	d0000 0000b	Read PWM frequency
RDUTY	13h	d0000 0000b	Read FAN duty factor
RGPIO	14h	1100 0000b	Read GPIO data
	15h	N/A	Reserved for future use
	16h	N/A	Reserved for future use
	17h	N/A	Reserved for future use
WCRIT	18h	N/A	Write T <sub>CRIT</sub> limit
WPROT	19h	N/A	Write write-once protection byte
WFREQ	1Ah	N/A	Write PWM frequency
WDUTY	1Bh	N/A	Write FAN duty factor
WGPIO	1Ch	N/A	Write GPIO data
RFU	1Dh-FDh	N/A	Reserved for future use
ID Codes			
MFG ID	FEh	Least Sig Byte 0100 1101b	Manufacturing ID code = 4Dh, ASCII code for "M" (for Maxim)
DEV ID	FFh	Least Sig Byte 0000 0101b	Device ID code, specific to MAX1669

#### Table 3. Command Byte Bit Assignments

BIT	NAME	POR STATE	FUNCTION	
7 (MSB)	MASKO	0	Masks T <sub>HIGH</sub> , T <sub>LOW</sub> , and diode fault ALERT interrupts when high. If all three MASK_ bits are set high, ALERT interrupts are totally masked.	
6	STBY	0	Standby mode control bit. If high, the device immediately stops converting, forces FAI low, and enters standby mode. If low, the device continuously autoconverts at a 2Hz r	
5	POL	0	$\overline{\text{OVERT}} \text{ pin polarity control:} \\ 0 = \text{active low (low when T_{CRIT} is crossed)} \\ 1 = \text{active high} $	
4	MASK1	0	Masks I/O1 $\overline{\text{ALERT}}$ interrupts when high. Set MASK1 = 1 and connect a 10k to 100k pull-up resistor on I/O1 to configure I/O1 as an output.	
3	MASK2	0	Masks I/O2 $\overline{\text{ALERT}}$ interrupts when high. Set MASK2 = 1 and connect a 10k to 100k pull-up resistor on I/O2 to configure I/O2 as an output.	
2	FAN ON	0	Enables FAN duty factor override when high.	
1		1	Must be "1"	
0	RFU	0	Reserved for future use	

#### Table 4. Configuration Byte Bit Assignments

#### Table 5. PWM Frequency Data Byte Bit Assignments (Write Command = 1Ah)

BIT	NAME	POR STATE		FU	NCTION
7 (MSB)	F3	0	Frequency <b>F3-F0</b> 0000b 0001b 0010b 0010b 0101b 0100b 0110b 0110b 1000b 1001b 1000b 1010b 1010b 1100b 1100b 1110b 1110b 1111b	<pre>/ control bit. F3–F0 are decoded Frequency (SYNC = GND) 20Hz 30Hz 40Hz 50Hz 60Hz 70Hz 80Hz 90Hz 100Hz 110Hz 120Hz 130Hz 140Hz 150Hz 160Hz DAC Mode</pre>	as follows: <b>Synchronized Frequency (SYNC Clocked)</b> fsyNc/13100 fsyNc/8730 fsyNc/6550 fsyNc/5240 fsyNc/5240 fsyNc/3740 fsyNc/3740 fsyNc/3270 fsyNc/2210 fsyNc/2620 fsyNc/2620 fsyNc/2620 fsyNc/2180 fsyNc/2180 fsyNc/2180 fsyNc/1870 fsyNc/1750 fsyNc/1640
6	F2	0	Frequency	/ control bit	
5	F1	0	Frequency	/ control bit	
4	F0	0	Frequency	/ control bit	
3–0	RFU	0	Reserved	for future use	

set to 1111b. The FAN duty factor can be selected from 0% to 100% in increments of 6.67%.

#### FAN Output in DAC Mode

If the PWM frequency register is set to code 1111b, the DAC is multiplexed to the FAN output and the FAN duty factor register (Table 6) now controls the DAC output

voltage rather than the duty factor. In DAC mode, the output swing is 0 to  $0.94 \cdot V_{CC}$  (out of 4 bits of resolution). To ensure a smooth transition, make sure that the FAN duty factor code is 0000b prior to setting the PWM frequency code for DAC mode (1111b). External circuitry must accept an initial FAN DAC voltage of 0.



BIT	NAME	NAME			FUNCTION	
			FAN duty-factor control bit. D3–D0 are decoded as follows:			
			D3–D0	Duty	V <sub>OUT</sub> (nominal)	
			0000b	0%	OV	
			0001b	6.67%	0.0625 • V <sub>CC</sub>	
			0010b	13.33%	0.125 • V <sub>CC</sub>	
			0011b	20%	0.1875 • V <sub>CC</sub>	
			0100b	26.67%	0.25 • V <sub>CC</sub>	
			0101b	33.33%	0.3125 • V <sub>CC</sub>	
7 (MSB)	D3	0	0110b	40%	0.375 • V <sub>CC</sub>	
· · · · ·			0111b	46.67%	0.4375 • V <sub>CC</sub>	
			1000b	53.33%	0.5 • V <sub>CC</sub>	
			1001b	60%	0.5625 • V <sub>CC</sub>	
			1010b	66.67%	0.625 • V <sub>CC</sub>	
			1011b	73.33%	0.6875 • V <sub>CC</sub>	
			1100b	80%	0.75 • V <sub>CC</sub>	
			1101b	86.67%	0.8125 • V <sub>CC</sub>	
			1110b	93.33%	0.875 • V <sub>CC</sub>	
			1111b	100%	0.9375 • V <sub>CC</sub>	
6	D2	0	FAN duty-fa	actor control bit		
5	D1	0	FAN duty-factor control bit			
4	D0	0	FAN duty-factor control bit			
3–0	RFU	0	Reserved for future use			

#### Table 6. Fan Duty-Factor Data Byte Bit Assignments (Write Command = 1Bh)



Figure 4. GPIO Logic Diagram

#### **GPIO Data Register**

I/O1 and I/O2 are configured through the GPIO data register and CONFIG byte register (Table 7 and Table 3). Upon power-up, the GPIOs are set as inputs. To ensure the I/Os are configured as inputs, set the state of the DATA1 and DATA2 bits high within the GPIO data register for I/O1 and I/O2, respectively. Figure 4 shows that by setting the GPIO DATA\_ bits high, the open-drain FET connected to the I/O\_ pins goes high impedance. Next, clear the MASK1 and MASK2 bits low within the  $\underline{\text{CONFIG}}$  byte register to remove the masks on the ALERT interrupts for I/O1 and I/O2, respectively.

To use I/O1 or I/O2 as an output, first set the MASK1 and MASK2 bits high, respectively. Setting the MASK\_ bits high within the CONFIG byte register masks out the corresponding I/O ALERT interrupts. Since the internal FETs are open-drain, a pull-up resistor is required from I/O\_ to V<sub>CC</sub>. The DATA1 and DATA2 bits within the GPIO data register directly control the state of the outputs of I/O1 and I/O2, respectively (Figure 4).



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#### Table 7. GPIO Input/Output Data Byte Bit Assignments

BIT	NAME	POR STATE	FUNCTION	
7 (MSB)	DATA1	1	For I/O1 configured as an output (MASK1 bit set high and a pull-up resistor on I/O1), this bit corresponds to the GPIO DATA1 block in Figure 4 and controls the output state of I/O1. To configure I/O1 as an input, set this bit high and clear the MASK1 bit low (Figure 4).	
6	DATA2	1	For I/O2 configured as an output (MASK2 bit set high and a pull-up resistor on I/O2 ), this bit corresponds to the GPIO DATA2 block in Figure 4 and controls the output state of I/O2. To configure I/O2 as an input, set this bit high and clear the MASK2 bit low (Figure 4).	
5–0	RFU	0	Reserved for future use	

#### Table 8. Write-Once Protection Byte Bit Assignments

BIT	NAME	POR STATE	FUNCTION
7 (MSB)	PROT1	0	Write-protects the T <sub>CRIT</sub> limit threshold register when high.
6	PROT2	0	Write-protects certain bits in the configuration register when high: - STBY standby-mode control (bit 6) - POL polarity control (bit 5) - FAN ON control (bit 2)
5	PROT3	0	Write-protects bit 7 in the GPIO register when high (DATA1).
4	PROT4	0	Write-protects bit 6 in the GPIO register when high (DATA2).
3–0	RFU	0	Reserved for future use

#### Write-Once Protection

Write-once protection allows the host BIOS code to configure the MAX1669 and protect against data corruption in the host that might cause spurious writes to the MAX1669. In particular, write protection allows a foolproof overtemperature override that forces the fan on, independent of the host system whether in DAC mode or PWM mode. The bits in the write-protection register (Table 8), once set high, cannot be reset low except by power-on reset.

Having a separate write-protect master register rather than making the actual registers themselves write once allows the host to read back and verify each register's contents before applying final write protection. Having individual write-protect control over different registers allows flexibility in application; for example, the TCRIT and configuration register could be protected while leaving one or both GPIO outputs free to be used as actuators.

#### **Status Byte Functions**

The status byte register (Table 9) indicates which (if any) temperature thresholds have been exceeded. The

status byte also indicates changes in GPIO states and transitions and whether there is a fault in the remote diode DXP-DXN path. After POR, the normal state of all the flag bits is 0, assuming none of the alarm conditions are present. Bits 2 to 5 of the status byte are cleared by *any* successful read of the status byte. Note that the ALERT interrupt latch is not automatically cleared when the status flag bit is cleared.

#### **Manufacturer and Device ID Codes**

This code identifies the functional capabilities of a particular device. New devices having enhanced or reduced software or hardware capabilities must be assigned a new code. The device ID allows the host system to interrogate the device to determine its capabilities, and use extra features if they're available. The device ID code is 2 bytes, for a total of 256X256 possible combinations. The device ID codes are located at command code 1111 1111b (FFh). If a read-byte operation (as opposed to a read-word) is applied to the device, it returns the least-significant byte correctly without the most-significant byte. Table 10 shows the device ID code for the MAX1669.



BIT	NAME	FUNCTION		
7 (MSB)	I/O1	This bit indicates the current state of I/O1 (unlatched).		
6	I/O2	This bit indicates the current state of I/O2 (unlatched).		
5	TRAN1*	This bit is set if a low-to-high or high-to-low transition has occurred at I/O1 (regardless of the state of the mask bits).		
4	TRAN2*	This bit is set if a low-to-high or high-to-low transition has occurred at I/O2 (regardless of the state of the mask bits).		
3	RHIGH*	A high indicates that the high-temperature alarm has activated		
2	RLOW*	A high indicates that the low-temperature alarm has activated.		
1	DIODE	A high indicates a remote-diode fault (open-circuit, shorted diode, or DXP short to GND).		
0 (LSB)	OVERT	When the T <sub>CRIT</sub> threshold is crossed, this bit goes high. The polarity of this bit does not depend on the POL bit (bit 5 in configuration byte).		

#### Table 9. Status Byte Bit Assignments

\*TRAN1 and TRAN2 alarm flags stay high until cleared by POR or until the status byte register is read. RHIGH and RLOW alarm flags stay high until cleared by POR or the temperature fault is removed and the status byte is read.

#### Table 10. Device ID Code

MAX1669 ID CODE			
LS BYTE LSBs MSBs	MS BYTE LSBs MSBs		
0000 0101	0000 0000		

# Table 11. Slave Address Decoding (ADD\_ Pins)

ADD0	ADD1	ADD2	ADDRESS
GND	GND	GND	0011 000b
GND	GND	Vcc	0011 001b
GND	Vcc	GND	0011 010b
GND	Vcc	Vcc	0101 001b
Vcc	GND	GND	0101 010b
Vcc	GND	Vcc	0101 011b
Vcc	Vcc	GND	1001 100b
V <sub>CC</sub>	V <sub>CC</sub>	V <sub>CC</sub>	1001 101b

#### **Slave Addresses**

The MAX1669 appears to the SMBus as one device having a common address for the temperature sensor section, GPIO section, and fan-control section. The device address can be set to one of eight different values by pin-strapping ADD\_ pins so that more than one MAX1669 can reside on the same bus without address conflicts (Table 11).

The MAX1669 also responds to the SMBus Alert Response slave address (see the *Alert Response Address* section).

#### **POR and UVLO**

The MAX1669's memory is volatile. To prevent ambiguous power-supply conditions from corrupting the data in memory and causing erratic behavior, a POR voltage detector monitors V<sub>CC</sub> and clears the memory if V<sub>CC</sub> falls below 1.85V (typical, see the *Electrical Characteristics* table). When power is first applied and V<sub>CC</sub> rises above 1.9V (typ), the logic blocks begin operating; although reads and writes at V<sub>CC</sub> levels below 3V are not recommended. A second V<sub>CC</sub> comparator, the ADC UVLO comparator, prevents the ADC from converting until there is sufficient headroom (V<sub>CC</sub> = 2.8V typ).

#### **Power-Up Defaults**

- Interrupt latch is cleared.
- ADC begins autoconverting at a 2Hz rate.
- Command byte is set to 01h to facilitate quick remote receive-byte queries.
- T<sub>HIGH</sub> and T<sub>LOW</sub> registers are set to +127°C and -55°C limits, respectively.
- TCRIT register is set to +100°C.
- ALERT and OVERT are reset to high-Z state.
- Device is in low-frequency PWM mode, 20Hz setting.
- PWM output is off (duty factor set to 0%).
- I/O1, I/O2 are high-Z (configured as inputs).

#### **Applications Information**

#### **Remote Diode Selection**

Temperature accuracy depends on having a goodquality, diode-connected, small-signal transistor. Accuracy has been experimentally verified for all of the devices listed in Table 12. The MAX1669 can also directly measure the die temperature of CPUs and other ICs having on-board temperature-sensing diodes, such as the Intel Pentium II.

The transistor must be a small-signal type having a relatively high forward voltage; otherwise, the A/D input voltage range can be violated. The forward voltage must be greater than 0.25V at 10µA; check to ensure this is true at the highest expected temperature. The forward voltage must be <0.95V at 100µA; check to ensure this is true at the lowest expected temperature. Do not use large power transistors. Also, ensure that the base resistance is <100 $\Omega$ . Tight specifications for forward-current gain (+50 to +150, for example) indicate that the manufacturer has good process controls and the devices have consistent V<sub>BE</sub> characteristics.

Series resistance causes +1/2°C error per ohm. When monitoring the temperature of a remote unit's internal diode, ensure that trace series resistance does not introduce significant error.

#### **ADC Noise Filtering**

The ADC is an integrating type with inherently good noise rejection, especially of low-frequency signals such as 60Hz/120Hz power-supply hum. Micropower operation places constraints on high-frequency noise rejection; therefore, careful PC board layout and proper external noise filtering is required for high-accuracy

#### Table 12. Component Manufacturers

MANUFACTURER	MODEL NUMBER			
SOT23 BJT				
Central Semiconductor (USA)	CMPT3906			
Fairchild Semiconductor (USA)	MMBT3906			
Motorola (USA)	MMBT3906			
Rohm Semiconductor (Japan)	SST3906			
Samsung (Korea)	KST3906			
MOSFET N-CHANNEL				
International Rectifier (USA)	IRF7201			
Fairchild Semiconductor (USA)	FDN359AN			
MOSFET P-CHANNEL				
International Rectifier (USA)	IRF7205			

**Note:** Transistors must be diode-connected (base shorted to collector).

remote measurements in electrically noisy environments.

High-frequency EMI is best filtered at DXP and DXN with an external 2200pF capacitor. This value can be increased to about 3300pF (max), including cable capacitance. Capacitance higher than 3300pF introduces errors due to the rise time of the switched-current source.

Nearly all noise sources tested cause the ADC measurements to be higher than the actual temperature, typically by +1°C to +10°C, depending on frequency and amplitude (see *Typical Operating Characteristics*).

#### **FAN Application Circuits**

In PWM mode, the output impedance at FAN is  $<50\Omega$ , enabling it to drive an N-channel MOSFET as shown in the *Typical Operating Circuit*. Return the source of the N-channel MOSFET to the system power ground, away from the ground of the MAX1669. For 3.3V applications, use low-threshold N-channel MOSFETs (Table 1).

In DAC mode, the FAN output can be linearly controlled (Figure 5). Upon power-up, the fan is off. The N-channel MOSFET is biased at the threshold of turning on. As  $V_{FAN}$  rises, the fan turns on linearly. To have the fan turned on at power-up, use the circuit shown in Figure 6.





Figure 5. Linear Fan Control (DAC Mode) with Fan "Off" at Power-Up



Figure 6. Linear Fan Control (DAC Mode) with Fan "On" at Power-Up





Figure 7. SMBus Write Timing Diagram





M/X/M

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#### **Typical Operating Circuit**

**MAX1669** 



#### Chip Information

TRANSISTOR COUNT: 12,924

**MAX1669** 



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